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IN THE DRAWINGS

Attached are eight (8) replacement sheets of drawings that include amendments suggested by the Examiner.

Fig. 1 has been amended to add an arrow to the lead line from reference numeral 1 to denote the article generally. Reference numeral 18 has been moved to more accurately designate the outer surface of the bodyside liner. The outline of the waist elastic members indicated by reference numeral 8 and the corresponding lead lines have been changed to dashed lines to denote corresponding underlying structures. Item 15 has been deleted from Fig. 1 as this reference number is not referred to in the specification.

Fig. 2 has been amended to add an arrow to the lead line from reference numeral 1 to denote the article generally. Corresponding directional arrows have been added to indicate the CD direction and MD direction of the article. The reference numeral indicating the longitudinal direction of the article has been changed from 61 to 62 to avoid the duplicate use of reference numerals in the specification.

Figs. 3-5 have been amended to add an arrow to the lead line from reference numeral 1 to denote the article generally. The lead line for reference number 48 has been changed to a dashed line to denote underlying structure and the reference numeral 2 has been removed from the drawings.

Figs. 6-8 have been revised to formalize the drawings. No substantive changes have been made to these Figures.

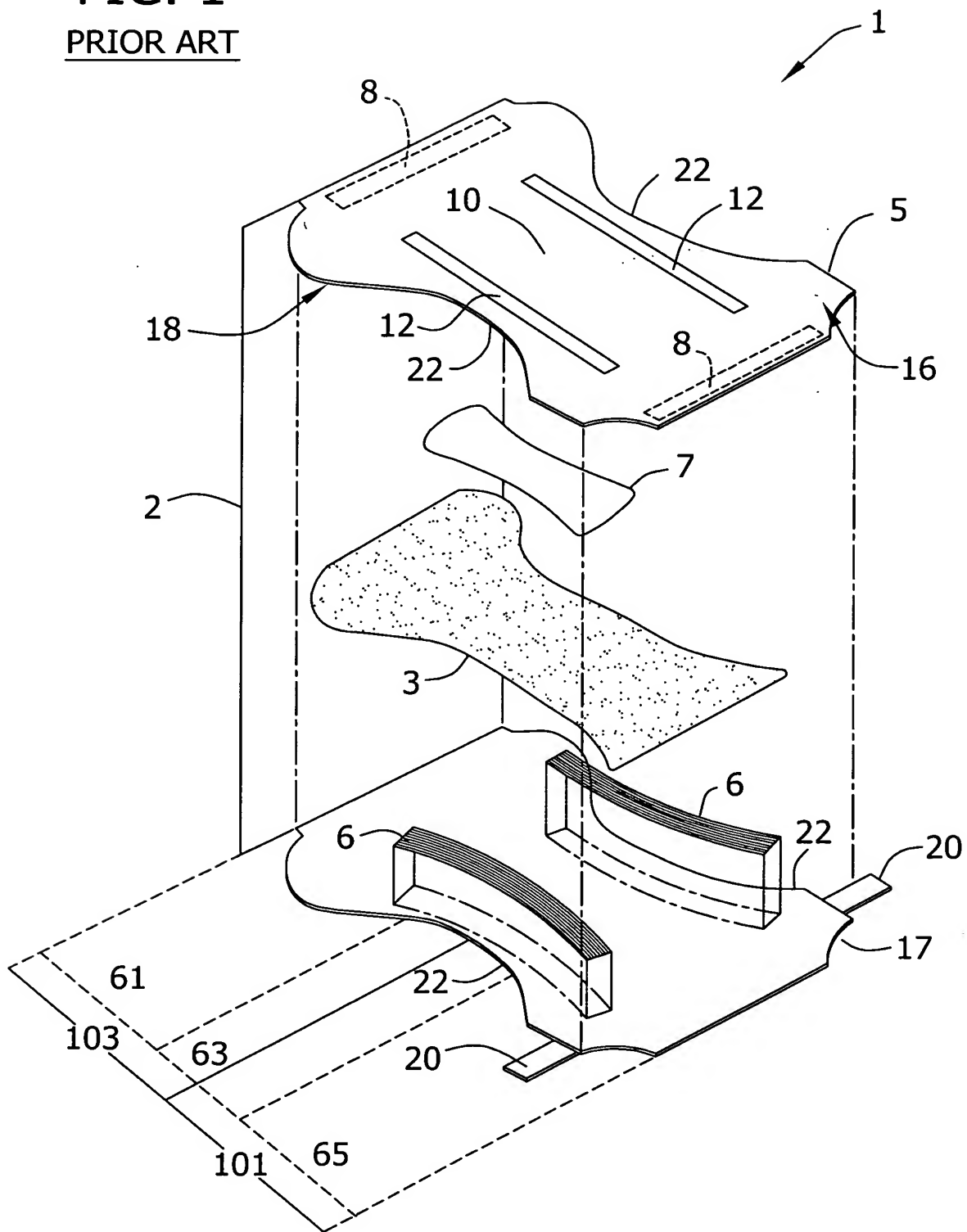


FIG. 2

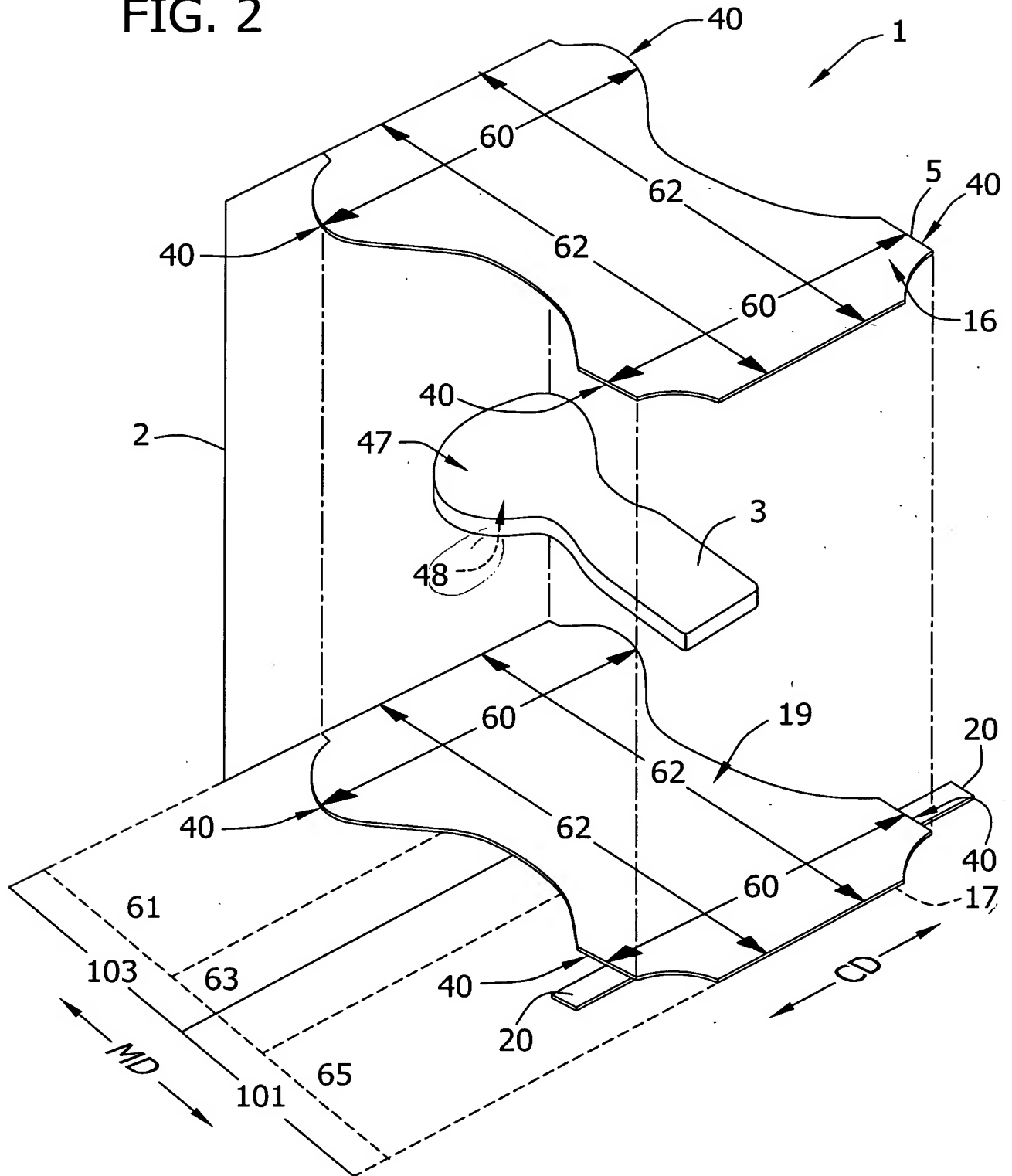


FIG. 1 is a perspective view of a semiconductor device 1. The device includes a substrate 101 with a patterned layer 103. A central region 3 is defined by a grid pattern 35, surrounded by a cross-hatched region 47. A dashed line 48 indicates a boundary. Other regions are labeled 61, 63, 65, 71, 73, 77, 79, 81, 83, 85, 87, 89, and 19. Arrows indicate the CD (Critical Dimension) and MD (Mask Dimension) directions.



FIG. 4

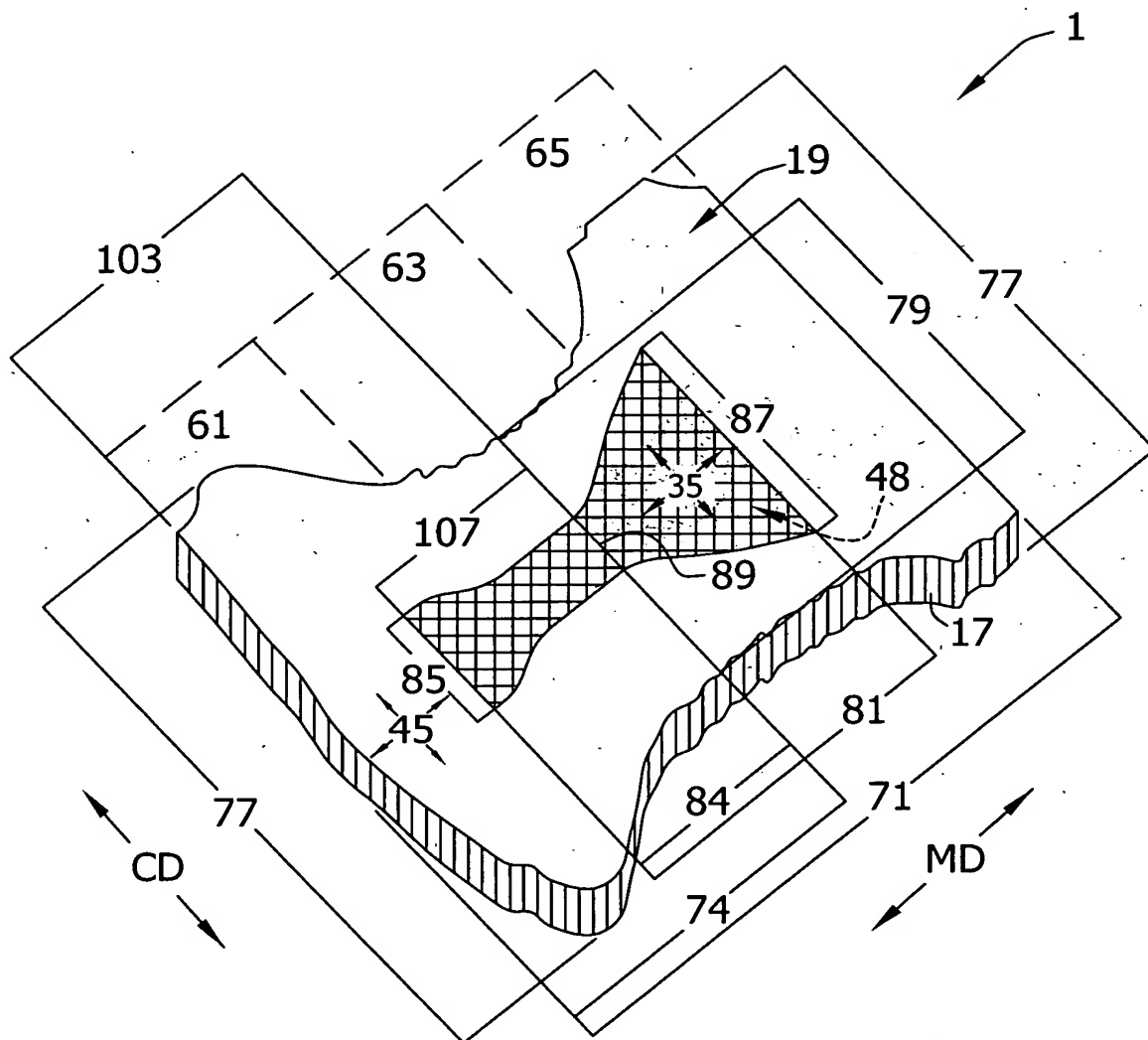
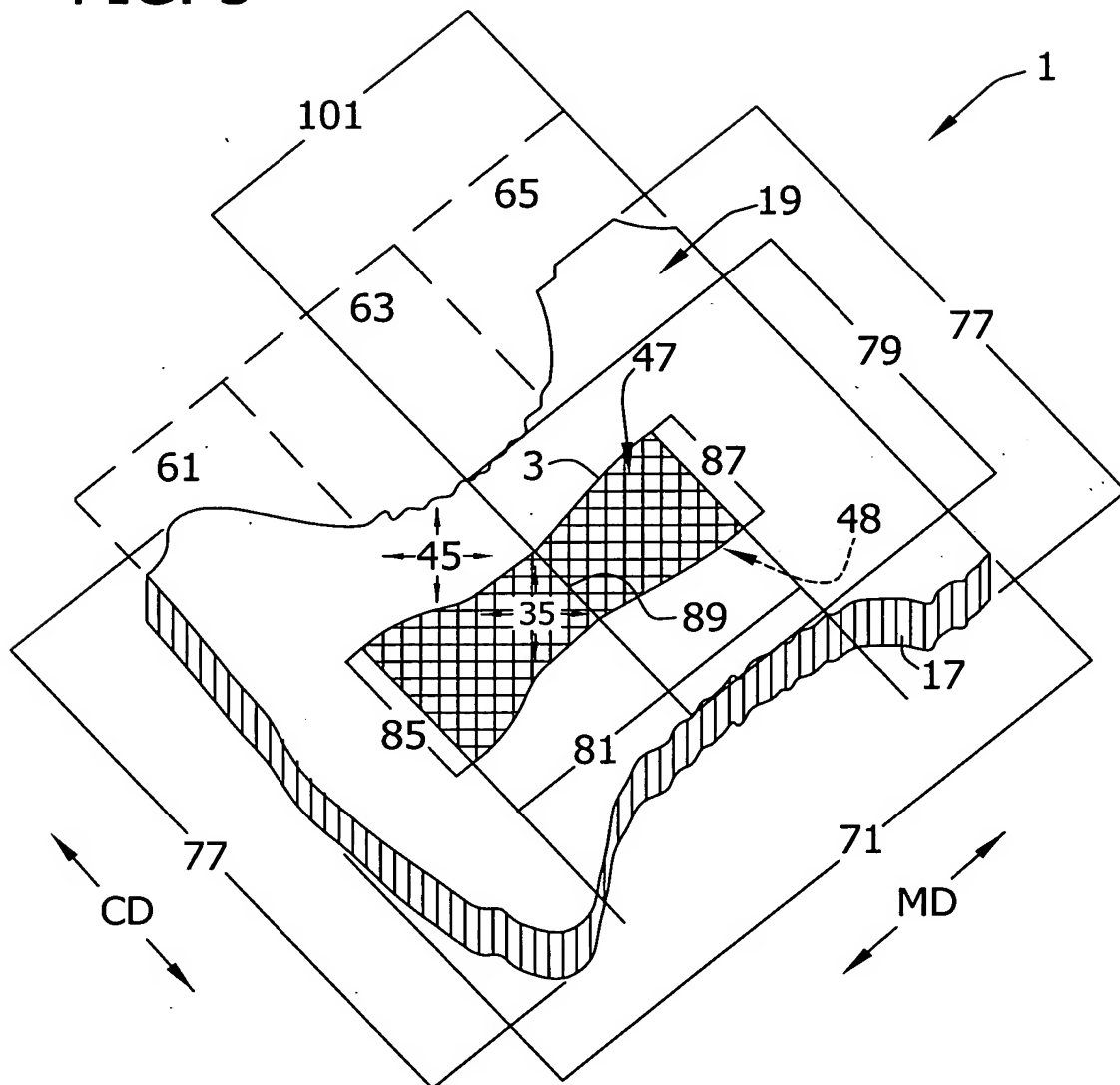
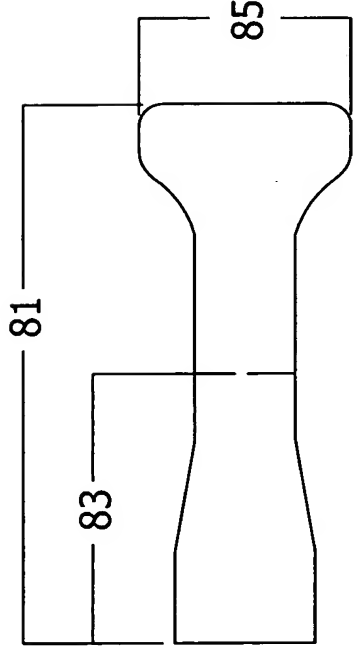
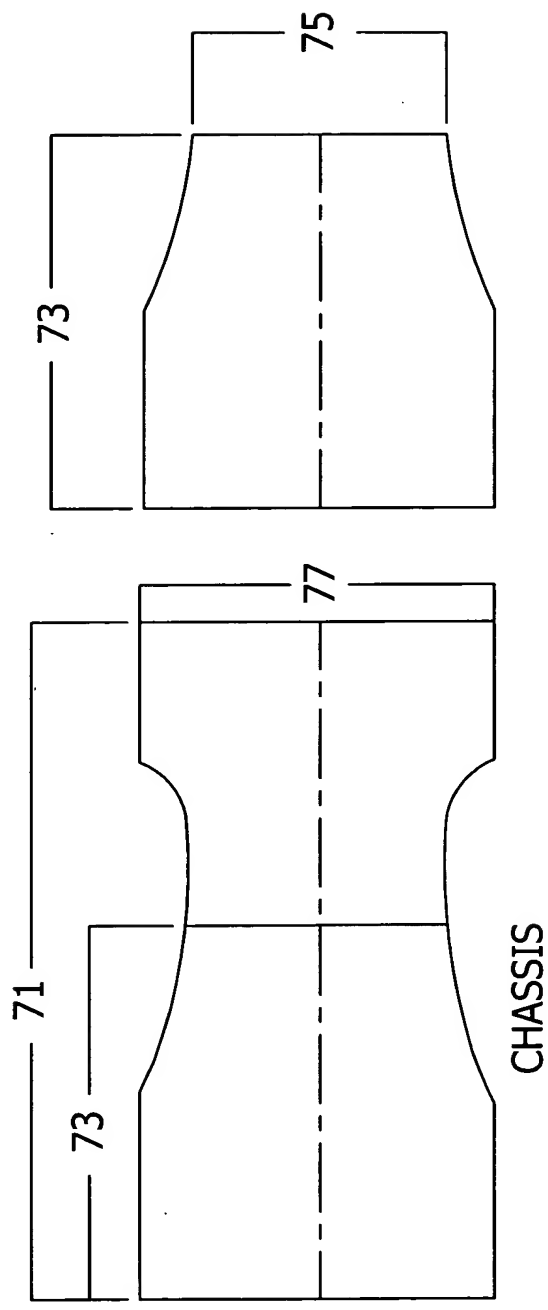


FIG. 5



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CLASS SUBCLASS

FIG. 6



ABSORBENT CORE

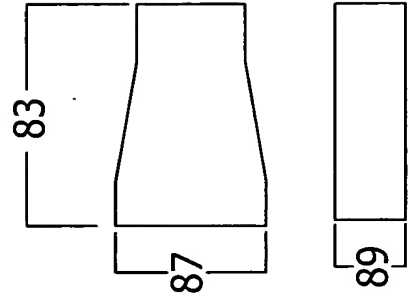
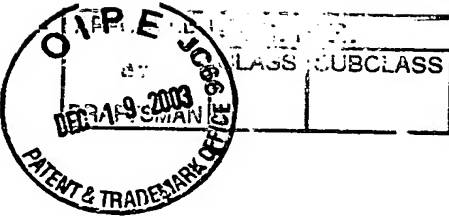




FIG. 7

TABLE 1	RATION OF THE ABSORBENT AREA TO EXTENSIBLE CHASSIS AREA @ 0%	RATION OF THE ABSORBENT AREA TO EXTENSIBLE CHASSIS AREA @ 16%	RATION OF THE ABSORBENT AREA TO EXTENSIBLE CHASSIS AREA @ 29%
MEAN % STRAIN @ 500g	21.8	17	13.1
MEAN % STRAIN @ 1000g	40.4	33.3	27.5
MEAN % STRAIN @ 1400g	47.7	41.8	37.8
STDV % STRAIN @ 500g	1.0	1.0	0.6
STDV % STRAIN @ 1000g	1.9	1.3	1.0
STDV % STRAIN @ 1400g	2.7	1.0	1.3



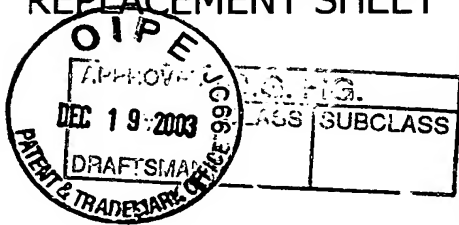
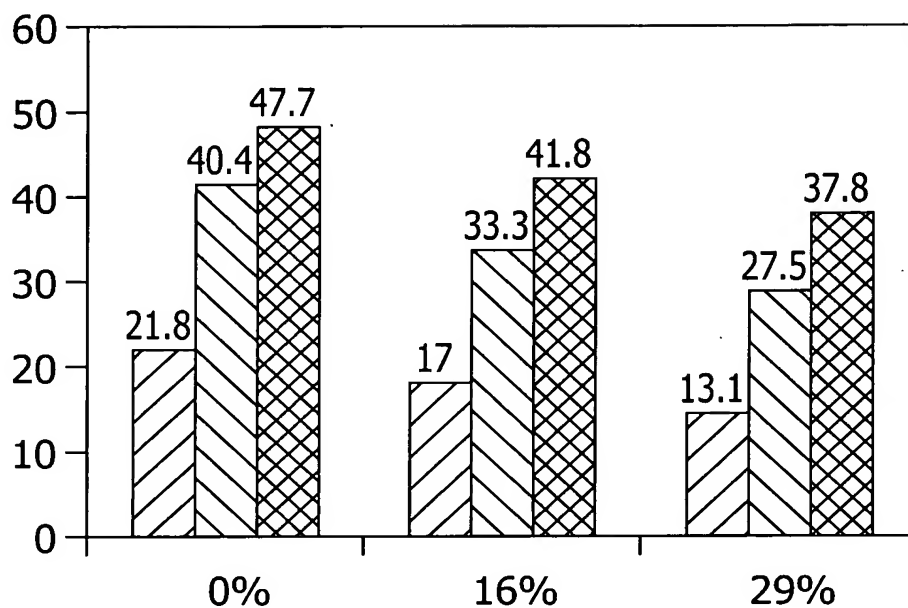





FIG. 8



-  MEAN % STRAIN @ 500g
-  MEAN % STRAIN @ 1000g
-  MEAN % STRAIN @ 1400g